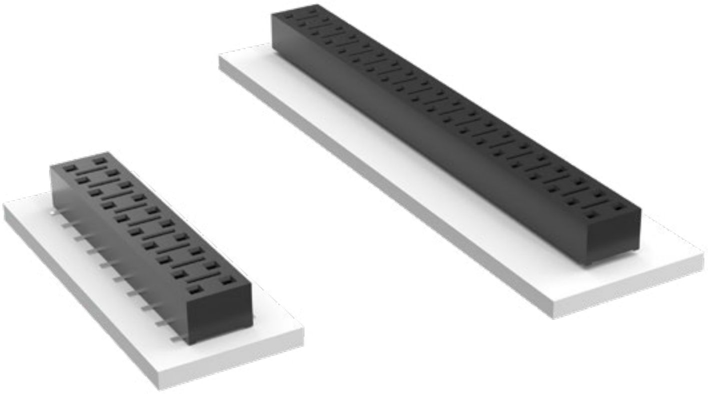
TIGER™ BEAM CONTACT

COST-EFFECTIVE RELIABLE SOCKET

(2.54 mm) .100" PITCH • HLE SERIES



HLE
Board Mates:
TSW, MTSW, DW, EW, ZW, TLW, TSM, MTLW, HW

HLE	1	NO. PINS PER ROW	02	PLATING OPTION	DV	TAIL OPTION	OTHER OPTION
		02 thru 50		**–F** = Gold flash on contact, Matte Tin on tail **–L** = 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail		Leave blank for Surface Mount (Requires –BE for Bottom Entry) **–TE** = Through-hole Top Entry **–PE** = Through-hole Pass-through Entry (Requires –BE for Bottom Entry)	**–BE** = Bottom Entry (Not available with –TE) **–A** = Alignment Pin (4 positions min.) Metal or plastic at Samtec discretion (Not available with -TE, -PE & -LC) **–LC** = Locking Clip (2 positions min.) (Not available with -A) (Manual placement required) **–K** = (6.50 mm) .256" DIA Polyimide Film Pick & Place Pad (3 positions min.) Not available with –TE or –PE tail option **–P** = Metal Pick & Place Pad (3 positions min.) **–TR** = Tape & Reel (29 positions max.) **–FR** = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

SPECIFICATIONS

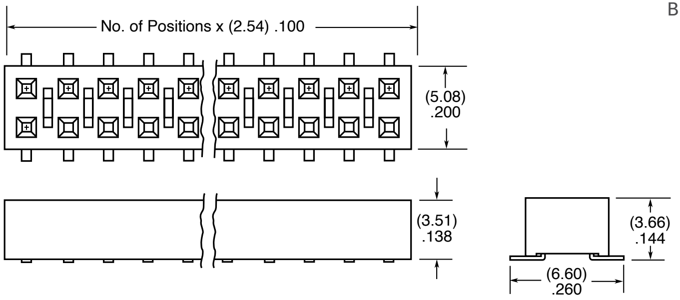
Insulator Material:
Black Liquid Crystal Polymer
Contact Material:
BeCu
Plating:
Au or Sn over 50 µ" (1.27 µm) Ni
Current Rating (HLE/TSM):
4.1 A per pin (2 pins powered)
Voltage Rating:
400 VAC
Operating Temp Range:
-55 °C to +125 °C
Insertion Depth:
(1.78 mm) .070" to (3.43 mm) .135" pass-through, or (2.59 mm) .102" min plus board thickness for bottom entry

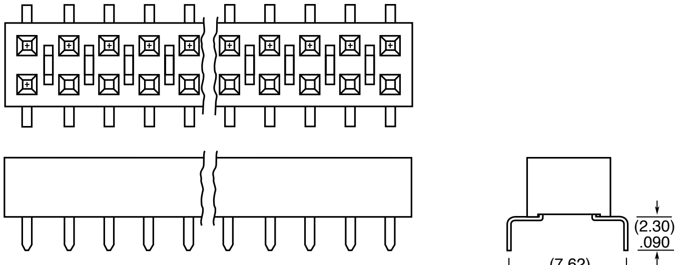
PROCESSING

Lead–Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (02-20)
(0.15 mm) .006" max (21-50)*
*(.004" stencil solution may be available; contact ipg@samtec.com)

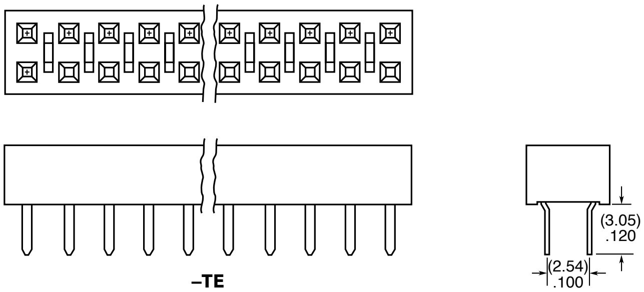
ALSO AVAILABLE
MOQ Required

Other Platings

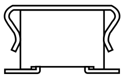




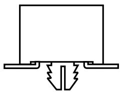
–PE



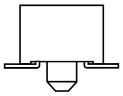
–TE



–P



–LC



–A

Note:
Some lengths, styles and options are non-standard, non-returnable.